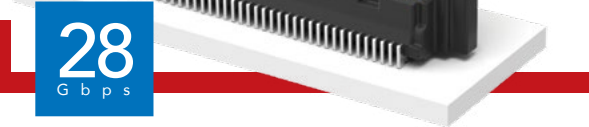




MICRO BLADE & BEAM SOCKET & HEADER

(0.40 mm) .0158" PITCH • A-SS4/A-ST4 SERIES



28
Gbps

A-SS4
Mates:
A-ST4

A-ST4
Mates:
A-SS4

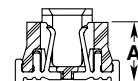
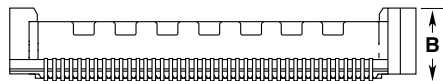
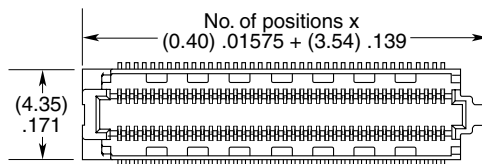
A-SS4	POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	K	TR
	-10, -20, -30, -40, -50	-3.00 = 3.00 mm -3.50 = 3.50 mm	-L = 10 μm (0.25 μm) Gold on contact, Matte Tin on tail		(Required in callout) -K = (3.50 mm) .138" DIA Polyimide Film Pick & Place Pad	(Required in callout) -TR = Tape & Reel

SPECIFICATIONS

Insulator Material:
Black LCP
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 μm (1.27 μm) Ni
Operating Temp Range:
-55 °C to +125 °C
Current Rating:
1.6 A per pin
(2 pins powered)

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max



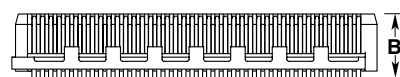
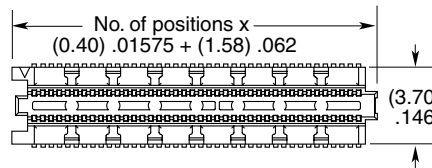
LEAD STYLE	A	B
-3.00	(2.85) .112	(3.50) .138
-3.50	(3.35) .132	(4.00) .157

A-ST4	POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	P	TR
	-10, -20, -30, -40, -50	-1.00 = 1.00 mm -1.50 = 1.50 mm -2.50 = 2.50 mm	-L = 10 μm (0.25 μm) Gold on contact, Matte Tin on tail		(Required in callout) -P = Pick & Place Pad	(Required in callout) -TR = Tape & Reel

MATED HEIGHT *

A-ST4 LEAD STYLE	A-SS4 LEAD STYLE	
	-3.00	-3.50
-1.00	(4.00 mm) .157"	(4.50 mm) .177"
-1.50	(4.50 mm) .177"	(5.00 mm) .197"
-2.50	(5.50 mm) .217"	(6.00 mm) .236"

*Processing conditions will affect mated height.



LEAD STYLE	A	B
-1.00	(1.00) .039	(3.08) .121
-1.50	(1.50) .059	(3.58) .141
-2.50	(2.50) .098	(4.58) .180

Note:
Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.